



Title of Change:	AR0230CS Production Data Sheet Update		
Effective date:	7 September 2015		
Contact information:	Contact your local ON Semiconductor Sales Office		
Type of notification:	ON Semiconductor will consider this change accepted.		
Change category:	<input type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input checked="" type="checkbox"/> Other Documentation Change		
Change Sub-Category(s): <div style="display: flex; justify-content: space-between;"> <div> <input type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Manufacturing Process Change </div> <div> <input type="checkbox"/> Material Change <input type="checkbox"/> Product specific change </div> <div> <input checked="" type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____ </div> </div>			
Sites Affected: <input type="checkbox"/> All site(s) <input checked="" type="checkbox"/> not applicable <input type="checkbox"/> ON Semiconductor site(s) : <input type="checkbox"/> External Foundry/Subcon site(s)			
Description and Purpose: Updated I/O timing (Table 6): Added min/max timing to Table 6 Removed Jitter specification Changed duty cycle Updated power dissipation (Table 9 through Table 18): Added min/max power Modified some typical power numbers Changed Tj to Ta in notes			
List of Affected Standard Parts: AR0230CSC00SUEA0-DRBR AR0230CSC00SUEAD3-GEVK AR0230CSC00SUEAH3-GEVB			